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ABSTRACT (Continue on reverse side if necessary and identify by black number)
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# Optical Emission Properties of Metal/III-V Semiconductor Interface States

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### **Abstract**

We report the first study of optical emission properties associated with formation of metal/III-V semiconductor interface states. Cathodoluminescence spectroscopy reveals discrete levels distributed over a wide energy range and localized at the microscopic interface. Our results demonstrate the influence of the metal, the semiconductor and its surface morphology on the energy distributions. Evolution of spectral features with interface formation, particularly above monolayer metal coverage, is correlated with Fermi level movements and Schottky barrier heights.

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The identification of interface states and their role in Schottky barrier formation have long been key issues in understanding electronic properties of metal/semiconductor (SC) junctions. For clean, ordered InP or GaAs (110), intrinsic gap surface states are absent, and a few monolayers of deposited metal create new charge states which stabilize the Fermi level (E<sub>F</sub>) in a limited range within the band gap2. Considerable spectroscopic evidence suggests that chemical effects (e.g., reaction and interdiffusion) take place concurrently which promote localized charge formation. Physical models for the localized charge states which influence metal/compound SC contact rectification vary from gap states due to defects formed by metal atom condensation3, to metal-induced gap states defined by the SC band structure4, to chemisorption and charge transfer involving metals atoms and clusters5, to chemically formed dipole layers6 and effective work functions of interface alloys7. Nevertheless, except for isolated absorption studies of surface and interface states by total internal reflection8 or surface photovoltage spectroscopy9 and near edge photoluminescence of mechanically-damaged surfaces 10, the presence and energies of interface states have been inferred largely from measurements of capacitance<sup>1,11</sup>, current<sup>1,12</sup>, and E<sub>F</sub> movement<sup>2-5</sup>.

Here we report the most direct observation of metal/SC interface states thus far. We have detected luminescence from interface states by means of cathodoluminescence spectroscopy<sup>13</sup> (CLS), a technique common to bulk studies and recently applied to laser-annealed metal/SC interfaces<sup>14</sup> and to GaAs/GaAlAs multilayer structures<sup>15</sup>. We have characterized the formation and evolution of interface states with metal deposition on UHV-cleaved (110) III-V SC surfaces of submonolayers up to several monolayers, where the metallic state of the overlayer is well defined. We show that dramatic changes are produced in the optical emission properties of III-V SC's upon metal deposition, both broad and discrete emission

bands at energies below the band gap. Our studies reveal the influence of the particular metal, the SC, its morphology and bulk growth quality on the spectral distribution. Furthermore, the evolution of electron-excited optical emission spectra of metal/InP or GaAs interfaces show qualitative differences at submonolayer vs. multilayer metal coverages which can be correlated to their E<sub>F</sub> movements and macroscopic Schottky barrier heights (SBH).

The CLS excitation was produced by a chopped electron beam from a glancing incidence electron gun impinging on a (110) crystal face. The room-temperature luminescence was focussed into a monochromator and the transmitted signal was phase-detected using a LN<sub>2</sub>-cooled Ge detector (North Coast) and a lock-in amplifier. Excitation depths on a scale of nanometers were achieved using low (500-3000 eV) incident electron energies at glancing angles<sup>14,16,17</sup>. As expected, interface specific features exhibited monotonic intensity increases relative to bulk features with decreasing excitation energy<sup>18</sup>. We evaporated metals on cleaved (110) single crystal surfaces of InP (n = 4.3x10<sup>15</sup> cm<sup>-3</sup>, p=10<sup>18</sup>cm<sup>-3</sup>) and GaAs (n = 4x10<sup>15</sup> cm<sup>-3</sup>) from Metal Specialties. A quartz crystal oscillator positioned next to the cleaved surface monitored film thicknesses. Injected electron concentration ranged from 10<sup>15</sup>- 10<sup>17</sup> cm<sup>-3</sup>. We raised injection levels to 10<sup>18</sup> cm<sup>-3</sup> in order to identify any effects of electron beam damages (which we found to be distinct from the spectral features reported here)<sup>18</sup>. Additionally, in situ photoluminescence spectra provided evidence for any bulk related features<sup>18</sup>.

Figure 1 shows CL spectra which illustrate the effect of submonolayer coverage on clean UHV-cleaved InP(110) surface for different metals and their similarity with step-cleaved features. We observe new emission features which indicate that metal deposition modifies the SC surface and forms new states. Similar features are observed for both p-type and n-type (not shown) InP (110). Within the energy range

0.6-1.6 eV, the CL spectra of clean InP shows only one emission centered at 1.35 eV, which corresponds to a near-band-gap (NBG) transition. Whereas for mirror-like areas there is no detectable emission in the energy region below the NBG transition over two orders of magnitude of injection level, the CL spectrum of step-cleaved areas shows weak emission at sub-band gap energies. The similarities in CL spectral shapes of step-cleaved areas and those from chemisorbed metals on mirror-like areas suggest that the initial metal deposition causes the formation of broken bonds, such as those formed during a step-cleavage process.

Multilayer metal deposition produces new spectral features which evolve differently for several metals. Fig. 2(a)-(d) demonstrate that the changes produced in the optical emission properties of InP upon metal deposition are strongly dependent on the particular metal. For Au deposition, Fig 2(a) exhibits significant new peak features at 0.8 eV and 0.96 eV, and a broad band whose energies extend up to the onset of the NBG transition. Deposition of 15 A of Au dramatically reduces the relative emission intensity at energies higher than 0.9 eV. Relative to Au, Cu deposition on InP(110), Fig. 2(b), produces interface states which exhibit a different spectral dependence on metal thickness, i.e., these interface states evolve faster with Cu versus Au thickness. This result is consistent with E<sub>F</sub> movements extracted from photoemission core level shifts for these interfaces, which showed a faster movement and stabilization for Cu versus Au19 over similar thickness ranges. The 0.78 eV emission is a common feature between the Au and Cu/InP interfaces. However, spectral differences are apparent at higher energies. In contrast, Fig. 2(c) shows that for Al deposition the NBG transition dominates the spectra even after deposition of 20 Å, whereas the low energy emissions are similar to those of Fig. 1. The overall luminescence intensity is drastically reduced, but Al deposition does not substantially change the spectrum. Similar low energy emission are found for Pd

deposition, Fig. 2(d), although the NBG transition is now totally suppressed. The p-InP specimens display lower overall luminescence efficiency than the n-type crystals, but the behavior of reactive metals such as Al, Pd, and Ni (not shown) differs only in the persistence of the NBG transition for Al. Sub-band gap spectral features appears to be roughly independent of doping.

Fig. 3 shows CL spectra of Au on cleaved GaAs (110). The mirror-like cleaved surface exhibits three strong emissions. a 1.42 eV emission corresponding to a NBG transition and lower energy peaks whose intensities depend on cleavage quality, doping, and doping level<sup>18</sup>. Deposition of Au causes a small shift of the 0.8 eV emission to lower energies, following by development of a peak centered at 0.75 eV which dominates the spectral shape after 15 Å of Au. The evolution of spectral features with metal deposition in both Figs. 2 and 3 demonstrate that strong changes in electronic state energies and densities take place at multilayer coverage which are not apparent in the lower coverage regime.

Metal deposition reduces the NBG luminescence intensity for all systems investigated, due in part to electron beam attenuation by the overlayer and to formation of a surface "dead layer" (ca.1000 - 4000Å) in which increasing band bending and width of the surface space charge region reduces bulk radiative recombination<sup>20,21</sup>. For coverages of only a few atomic layers, overlayer attenuation of 500-3000 eV electrons depends only weakly on the particular metal<sup>15</sup>. In contrast, the magnitude and rate of band bending changes depend sensitively on specific metal, and the NBG intensity attenuation in Figs 2(a)-(d) correlate strongly with E<sub>F</sub> movement with metal deposition measured by photoemission<sup>19</sup>. Thus, E<sub>F</sub> shifts slowly (rapidly) with Au (Cu) coverage<sup>19</sup>, producing large n-type band bending with 10-20 Å (2-4 Å) deposition, which reduces NBG luminescence intensity at a corresponding rate. Al deposition produces relatively little band bending<sup>12,19</sup>,

consistent with the NBG feature dominant after 20 Å coverage. The NBG intensity reduction observed for Pd/p-InP is also consistent with the large E<sub>F</sub> movement expected<sup>19</sup>.

Several possibilities exist for the physical nature of the observed metal-induced transitions. Initially, metal deposition perturbs the surface bonding and thereby the electronic structure of the semiconductor surface. However, with multilayer metal coverage, these states evolve into interface states with different energies and densities. At submonolayer coverages, these states can not be ascribed to metalinduced gap states' since the overlayers are not yet metallic. At higher coverages, the spectral shape also rules out surface amorphization, which would produce a structureless optical emission spectrum or a broad NBG wing. On the other hand, diffusion of the metal in the SC may cause the formation of a highly doped surface layer, which may account for the observed optical emission spectra. The high diffusion coefficient and macroscopic transport of Cu in InP, even at temperatures as low as 400°C" suggests that an indiffusion process may form a similar albeit microscopic layer even near room temperature. The qualitative difference between unreactive6 metals such as Au or Cu versus reactive metals such as Al or Ni may be attributed to the formation of a reacted interfacial layer which inhibits metal indiffusion in the latter case. However, we have not found clear correlation between the emission energies of the metal/InP interfaces and optical emission from the same metal-doped InP22,23. A recent luminescence investigation of Cu metal diffusion in InPi at various temperatures displayed formation of a neutral complex at 400°C which evolved with increasing temperature, giving rise to an intense band at ca. 1.0 eV versus our 0.78 eV band. The results suggest that isolated metal impurities within the SC are alone insufficient to account for the observed optical emission. More likely, metal indiffusion coupled with semiconductor outdiffusion of the

different species forms defect complexes (e.g., impurity-native defects) which are responsible for the optically-detected interface states.

The dominant CLS features at multilayer coverages in Figs. 2 and 3 can account for the reported SBH's of Au and Cu on n-InP (110) and Au on n-GaAs (110). Transitions from interface states into (out of) the valence (conduction) band as well as between localized states can contribute to the CL spectrum. Of these, transitions which have the valence band maximum as the final state have the highest probability since the upward band bending of n-type SC's results in accumulation of injected beam-excited valence holes at the interface. This fact also accounts for the lower overall CL efficiency observed for p-type specimens, where such hole accumulation is not in general expected. Thus, assuming that localized state transitions to the valence band maximum produce the dominant contribution to the n-type CL spectra and that recombination cross sections do not vary discontinuously with energy, the pronounced peak feature at 0.78 eV in Figs. 2(a) and (b) suggest a relatively high density of states located 0.58 eV below the conduction band edge. This value is close to the 0.43-0.5 eV SBH reported for Au and Cu on InP (110) and can account for the observed E<sub>F</sub> stabilization. Surface photovoltage spectra of Au on InP (110) supports this spectral interpretation, although CLS alone provides optical evidence at metallic coverages. Similarly, the evolution of CLS peaks in Fig. 3 to a single emission feature at 0.75 eV indicates a high density of states located 0.7 eV below the conduction band edge, compared with the reported SBH of 0.8-0.9 eV3. Of course, E<sub>F</sub> stabilization need not be precisely at a density-of-states peak but rather may be weighted or averaged toward such a value from the bulk E<sub>F</sub> position.

On the other hand, the more reactive Al/InP system displays a SBH  $\leq 0.2 \, \text{eV}^{12.19}$  which correlates well with the persistence of the NBG transition and weak sub-band gap emission detected.

We have observed the formation and evolution of metal/SC interface states by optical emission techniques. We were able to distinguish between interface states promoted by metal deposition from those of step-cleaved areas. The CL spectra show qualitative differences between metals, especially with different chemical reactivity. These metal-induced states are distributed over a wide energy range, are localized at the interface, and can differ substantially from those produced by only submonolayer metal coverages. Dominant CL features show interface levels at energies which can account for Schottky barrier heights.

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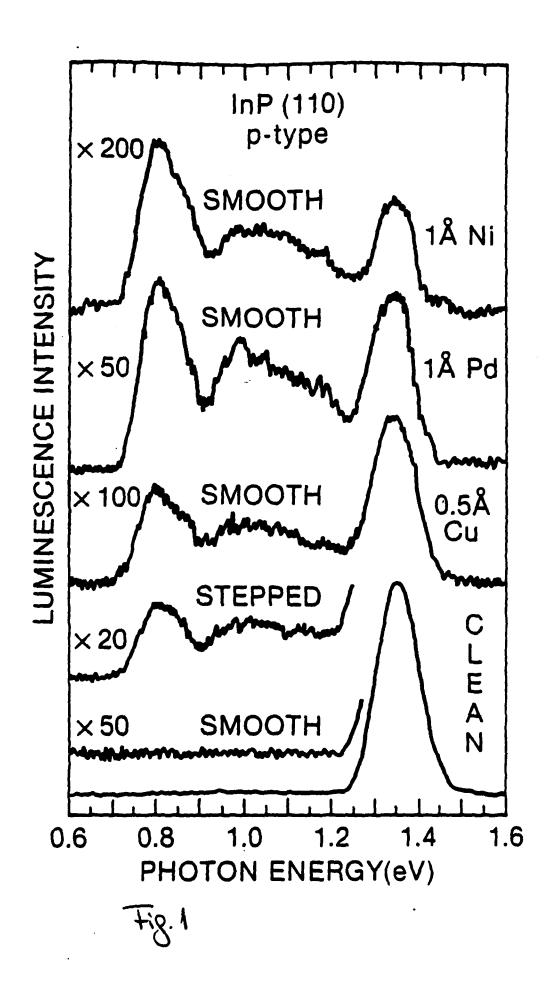
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## Figure Captions

- 1. CL spectra of clean, mirror-like p-InP (110) surfaces before and after submonolayer Ni, Pd, or Cu deposition, and the clean step-cleaved surface.
- 2. CL spectra of (a) Au, (b) Cu, and (c) Al on clean, mirror-like n-InP (110) and (d)
  Pd on clean mirror-like p-InP (110) as a function of deposition.
- 3. Cl spectra of clean, mirror-like n-GaAs (110) with increasing Au deposition.



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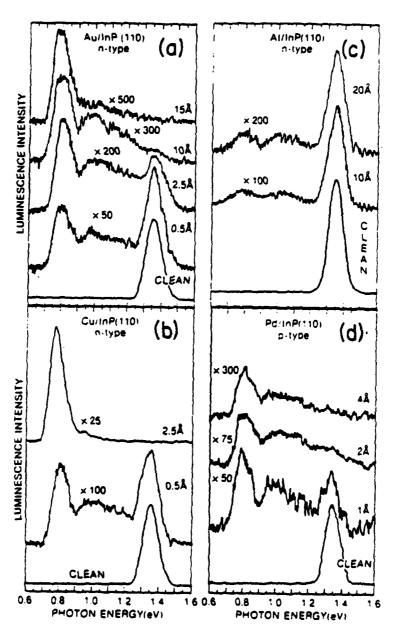
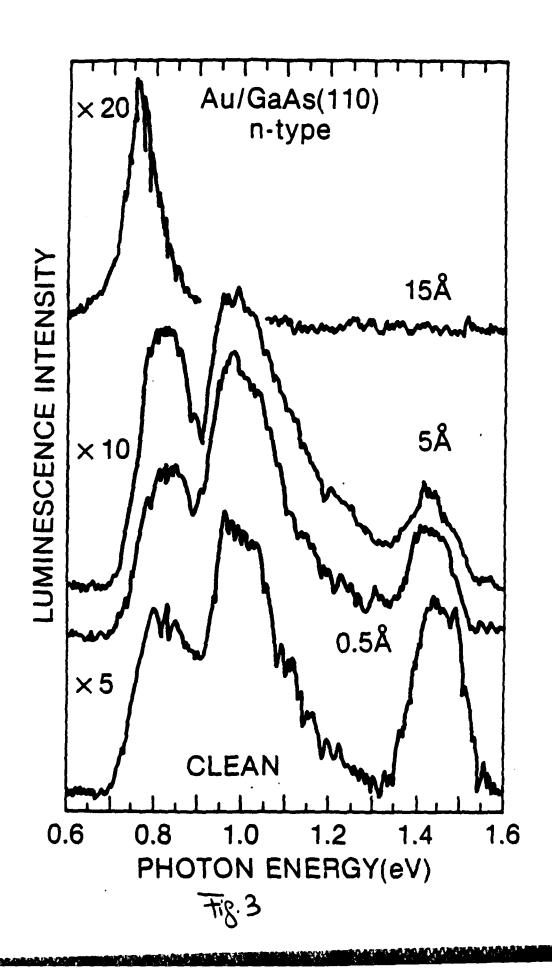


Fig. 2



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